

Title (en)
AN ELECTRONIC ASSEMBLY AND A METHOD FOR MANUFACTURING THE SAME

Title (de)
ELEKTRONISCHE BAUGRUPPE UND VERFAHREN ZU IHRER HERSTELLUNG

Title (fr)
ENSEMBLE ELECTRONIQUE ET PROCEDE DE FABRICATION DE CE DERNIER

Publication
EP 1459610 A1 20040922 (EN)

Application
EP 02793728 A 20021219

Priority
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• SE 0104335 A 20011219

Abstract (en)
[origin: WO03053115A1] An electronic assembly and a method of manufacturing such an assembly in which a carrier 13 for electronic components 14 and leads 18 for external connection are connected with each other by interconnections 19 including solder joints 22. In order to sustain heating periods, at least one of said interconnections comprises an adhesive joint 23 in addition to the solder joint applied between the carrier and one lead.
[origin: WO03053115A1] An electronic assembly and a method of manufacturing such an assembly in which a carrier (13) for electronic components (14) and leads (18) for external connection are connected with each other by interconnections (19) including solder joints (22). In order to sustain heating periods, at least one of said interconnections comprises an adhesive joint (23) in addition to the solder joint applied between the carrier and one lead.

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CPC (source: EP)
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Citation (search report)
See references of WO 03053115A1

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